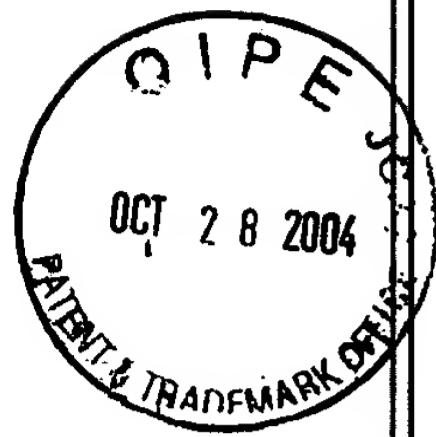


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant(s): Lee John Smith et al.

Assignee: Amkor Technology, Inc.

Title: THIN SEMICONDUCTOR PACKAGE INCLUDING STACKED DIES

Serial No.: 09/944,732 Filed: August 31, 2001

Examiner: David E. Graybill Group Art 2822
Unit:

Docket No.: G0079

Monterey, CA
October 22, 2004

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO REQUIREMENT FOR INFORMATION

Dear Sir:

This is response to the Requirement for Information
(Requirement) dated August 18, 2004:

1. **Remarks** begin on page 2 of this paper.